

Title (en)

Method for injection moulding articles having at least one hollow section

Title (de)

Verfahren zum Spritzgiessen von mindestens einen Hohlraum aufweisenden Formteilen

Title (fr)

Procédé pour mouler par injection des pièces comportant au moins une partie creuse

Publication

EP 1127674 B1 20031105 (DE)

Application

EP 01103313 A 20010213

Priority

DE 10007994 A 20000222

Abstract (en)

[origin: JP2001232656A] PROBLEM TO BE SOLVED: To obtain a injection molding method requiring no expensive nitrogen, high in cooling effect and exerting no adverse effect on the quality of an obtained molded object and an apparatus therefor. SOLUTION: A molded object (2) having at least one gap (1) is injection- molded by filling a cavity (5) with a molten thermoplastic material without perfectly filling the cavity and injecting a fluid having large heat capacity in the molten thermoplastic material to perfectly coating the surface of the cavity (5). An injection molding apparatus has a means (13) for removing the fluid present in the gap (1) of the molded object (2) and uses the fluid having large heat capacity.

IPC 1-7

B29C 45/17

IPC 8 full level

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CPC (source: EP US)

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